

LIP/2814
#A/sub Spec. N
10/5/99
C. McKinney

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Konecni et al.
Serial No.: 08/988,686
Filed: 12/11/97



Docket No.: TI-22166
Art Unit: 2814
Examiner: Eaton, K.

For: **METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE**

Assistant Commissioner for Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

August 31, 1999

Jeff Quan

LETTER

Dear Sir:

With regard to the Office Action mailed May 28, 1999, and the Applicant's Response mailed August 30, 1999, and in connection with the above-identified application, Applicant respectfully submits the clean copy of the instant specification that was inadvertently omitted from the Response mailed yesterday. Please charge any necessary fees to the deposit account of Texas Instruments, Inc., Deposit Account No. 20-0668.

Respectfully submitted,

Mark A. Valetti
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Reg. No. 36,707

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